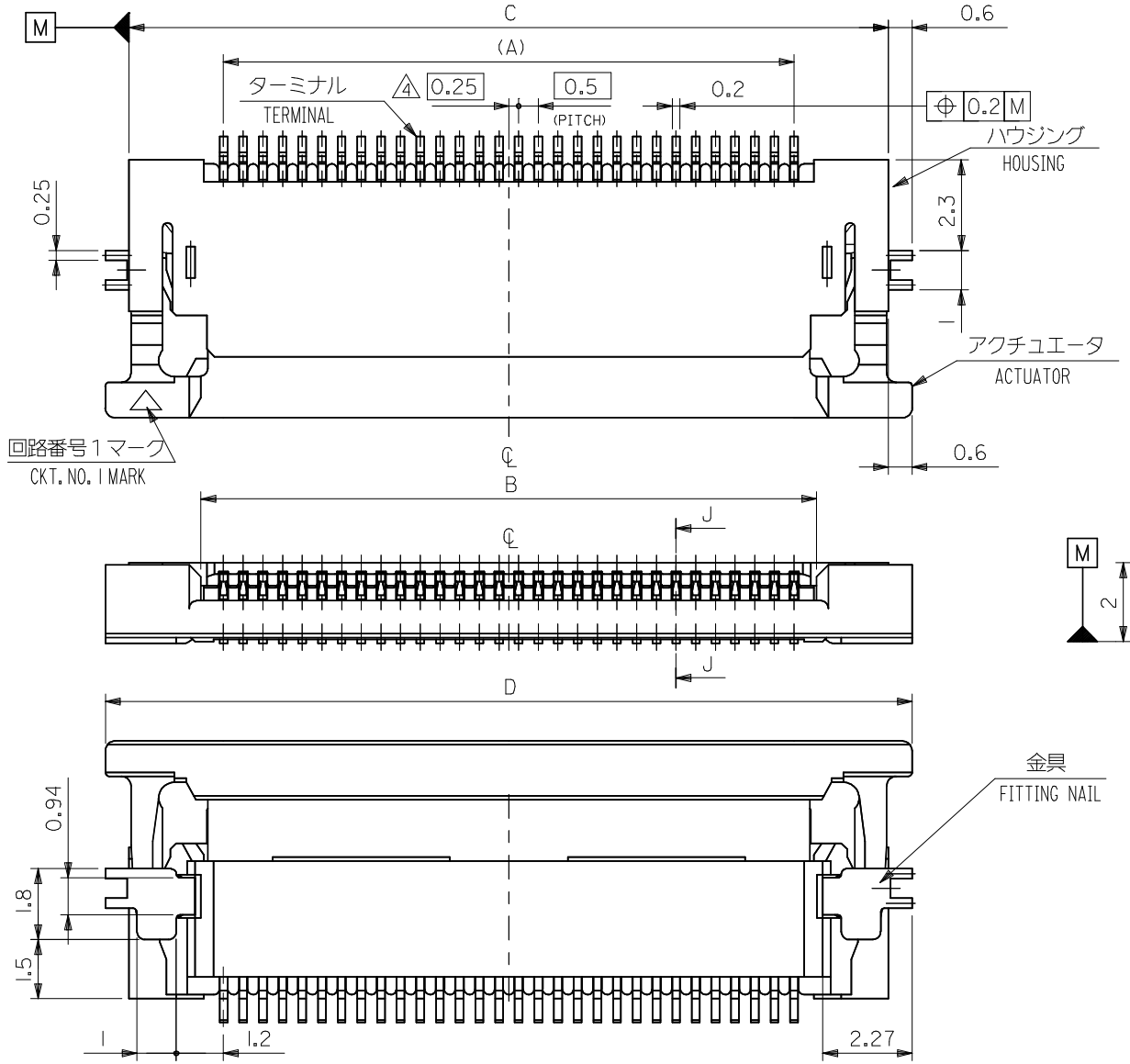
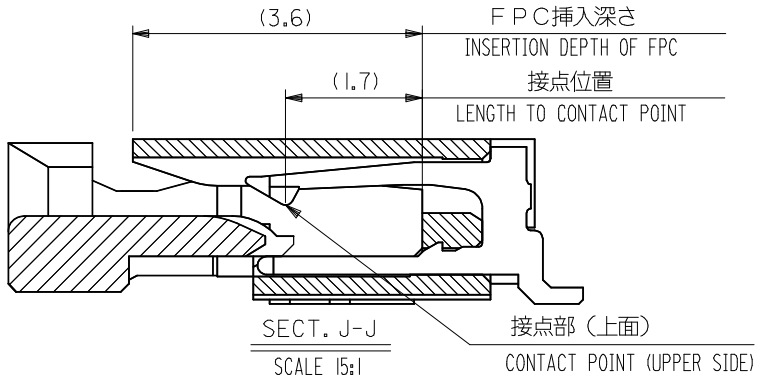
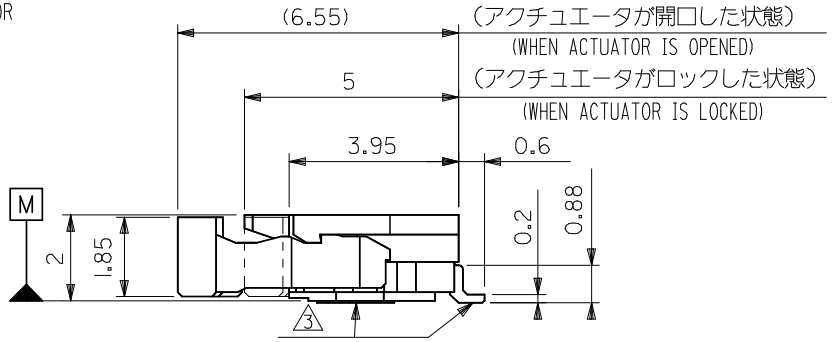






D	C	B	A	EMBOSSED TAPE ORDER No. オーダー番号	MATERIAL NO.	CIRCUIT
30.5	29.3	25.65	24.5	54104-5096	54104-5039	50
28.5	27.3	23.65	22.5	54104-4696	54104-4639	46
28.0	26.8	23.15	22.0	54104-4596	54104-4539	45
27.0	25.8	22.15	21.0	54104-4396	54104-4339	43
25.5	24.3	20.65	19.5	54104-4096	54104-4039	40
24.5	23.3	19.65	18.5	54104-3896	54104-3839	38
23.5	22.3	18.65	17.5	54104-3696	54104-3639	36
23.0	21.8	18.15	17.0	54104-3596	54104-3539	35
22.5	21.3	17.65	16.5	54104-3496	54104-3439	34
22.0	20.8	17.15	16.0	54104-3396	54104-3339	33
21.5	20.3	16.65	15.5	54104-3296	54104-3239	32
20.5	19.3	15.65	14.5	54104-3096	54104-3039	30

REVISED
EC NO: J2008-4308 2008/06/27
DRWN:MNABE1 2008/06/30
CH'KD:THARUYAMA 2008/06/30
APPR:NUKITA
DESCRIPTION
REV A

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: ---
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: Y.SAKIYAMA DATE: '04/01/22
CHECKED BY: M.SASAO DATE: '04/01/22
APPROVED BY: M.SASAO DATE: '04/01/22

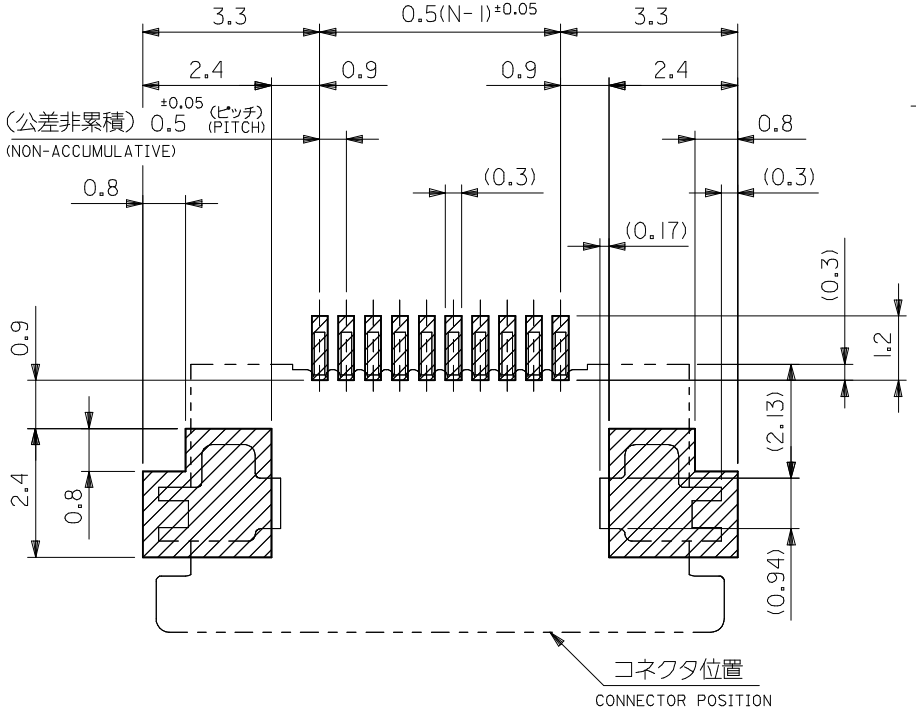
TITLE: 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT -LEAD FREE-

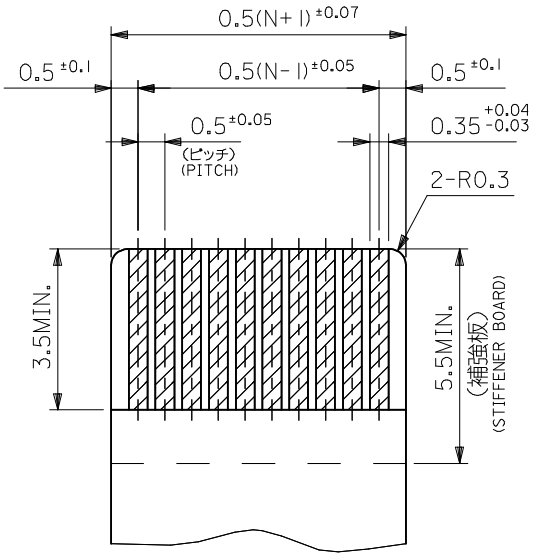
molex MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-54104-071
SHEET NO.: 1 OF 2

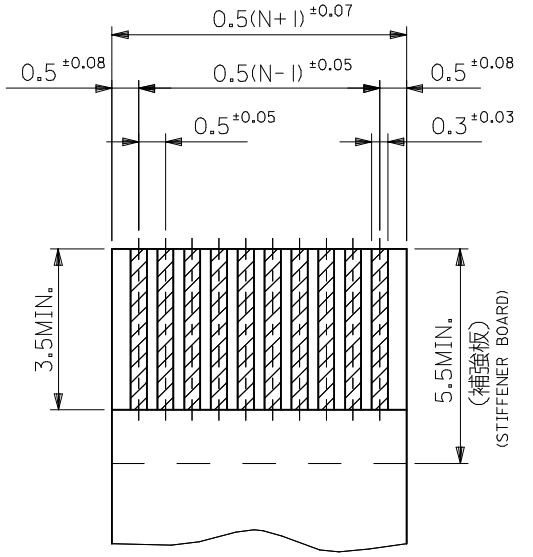
SIZE A3

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適合ＦＰＣ推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ：0.3±0.03)
(THICKNESS:0.3±0.03)



適合ＦＦＣ推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ：0.3±0.03)
(THICKNESS:0.3±0.03)

参考基板レイアウト
RECOMMENDED P.C.BOARD
PATTERN DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATERIAL

ハウジング HOUSING	：46ナイロン、UL94V−0 46NYLON
アクチュエータ ACTUATOR	：PPS、UL94V−0
ターミナル TERMINAL	：リン青銅、ニッケル下地 錫ビスマスメッキ（t＝0．2） PHOS-BRONZE,TIN-BISMUSTH OVER NICKEL PLATING.(t=0.2)
金具 FITTING NAIL	：リン青銅、ニッケル下地 錫メッキ（t＝0．2） PHOS-BRONZE,TIN OVER NICKEL PLATING.(t=0.2)

2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE,ACTUATOR OF PART NO.54104-**39 SHOULD BE LOCKED.

3. ソルダーテール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0．1 MAX．下方向 0．15MAX．とし、相互のバラツキ量は、0．1MAX。とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM UPPER DIRECTION: 0.1 MAX. , LOWER DIRECTION: 0.15MAX. H
OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.

4. 偶数極に適用。
APPLY FOR EVEN CIRCUIT.

5. パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

6. 本製品は 54104-**37 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 54104-**37.

ＦＰＣ／ＦＦＣについて

打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔３５マイクロメーターまたは５０マイクロメーター
メッキ厚 3〜9マイクロメーター錫または半田メッキ（電気メッキ）
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC.:
THICKNESS OF SOFT COPPER FOIL:
35 micrometer or 50 micrometer
TIN OR SOLDER PLATING:
3 ~9 micrometer(ELECTRICAL PLATING)

ＦＰＣについて

補強フィルム材質はポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED	EC NO:	DESCRIPTION	REV
	J2008-4308		A
DRWN:MNABE I	2008/06/27		
CH'KD:T. HARUYAMA	2008/06/30		
APPR:NUKITA	2008/06/30		

GENERAL TOLERANCES (UNLESS SPECIFIED)

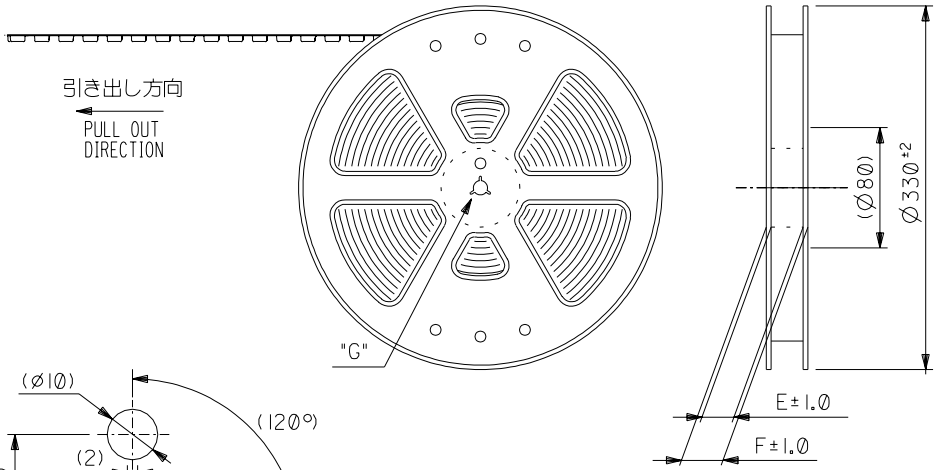
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

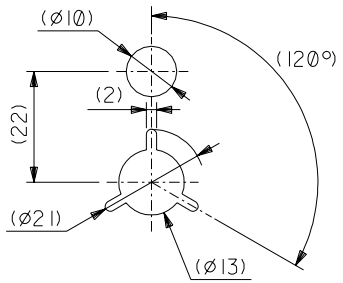
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	---
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY	Y.SAKIYAMA
DATE	'04/01/22
CHECKED BY	M.SASAO
DATE	'04/01/22
APPROVED BY	M.SASAO
DATE	'04/01/22
MATERIAL NO.	SEE SHEET 1
MODEL NO.	54104-**39
TITLE	0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT -LEAD FREE-
	MOLEX INCORPORATED
DOCUMENT NO.	SD-54104-071
SHEET NO.	2 OF 2
SIZE	A3

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DWG. NO. SD-54104-072

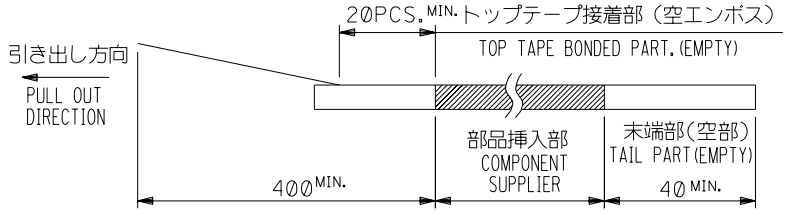




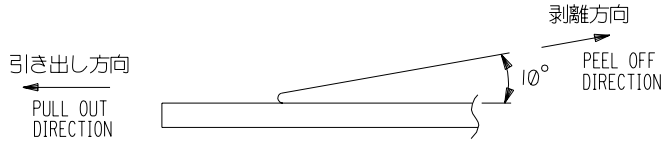
DETAIL "G"

NOTES

1. 梱包数量：１５００個／リール
   NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



3. トップテープの剥離強度：0.1～1.3N {10 ～ 130gf}
   （剥離方向は下図参照）
   尚、本規格値は出荷時に適用。（但し、輸送時に剥離が発生しないこと。）
   PEELING OFF FORCE OF TOP TAPE : 0.1～1.3N {10 ～ 130gf}
   (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
   THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
   PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



			30.8	31.9	26.1	29.6	54104-5096	50
			28.8	29.9	24.1	27.6	-4696	46
			28.3	29.4	23.6	27.1	-4596	45
			27.3	28.4	22.6	26.1	-4396	43
			25.8	26.9	21.1	24.6	-4096	40
			24.8	25.9	20.1	23.6	-3896	38
44	49.4	45.4	23.8	24.9	19.1	22.6	-3696	36
			23.3	24.4	18.6	22.1	-3596	35
			22.8	23.9	18.1	21.6	-3496	34
			22.3	23.4	17.6	21.1	-3396	33
			21.8	22.9	17.1	20.6	-3296	32
			20.8	21.9	16.1	19.6	54104-3096	30
キャリアテープ幅 CARRIER TAPE WIDTH	F	E	D	C	B	A	MATERIAL NO.	CIRCUIT

4. 材料(MATERIAL)
   キャリアテープ(CARRIER TAPE)：ポリプロピレン(POLYPROPYLENE)
   トップテープ(TOPTAPE)：PET , PE , PEF
   リール(REEL)：ポリスチレン(PS)<リサイクル材を含む>
   POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

5. 本製品は 54104-**92 の鉛フリー品である。
   THIS PRODUCT IS LEAD FREE OF 54104-**92.

DO NOT SCALE DRAWING

EC NO.
DRWN:
CH'K:
APPR:

EC NO.
DRWN:
CH'K:
APPR:

EC NO.
DRWN:
CH'K:
APPR:

REVISED '04/04/21
EC NO. J2004-3918
DRWN: Y.WADA
CH'K: M.SASAO
APPR: M.SASAO
A

RELEASED '04/01/22
EC NO. J2004-2032
DRWN: Y.SAKIYAMA
CH'K: M.SASAO
APPR: M.SASAO
0

DESCRIPTION
REV

MATERIAL 材料 注記参照 SEE NOTES

FINISH 仕上げ //

WIRE RANGE 適用電線範囲 //

INS. RANGE 被覆外径 //

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差

10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

SCALE —

MODEL NO. 54104-**96

DESIGN UNITS ☒mm ☐INCH

THIRD ANGLE PROJECTION

DIMENSIONS: ☐mm/INCH ☐INCH/mm ☒mm ONLY

SHT REV

REVISE ON CAD ONLY

DRAWN BY & DATE Y.SAKIYAMA '04/01/22

CHECKED BY & DATE M.SASAO '04/01/22

APPROVED BY & DATE M.SASAO '04/01/22

TITLE: Embstp Pkg for 0.5 FPC Conn Zif Hsg Assy -LEAD FREE-

molex MOLEX INCORPORATED

CAD FILENAME SD-54104-072.S01

MATERIAL NO. SEE CHART

DRAWING NO. SD-54104-072

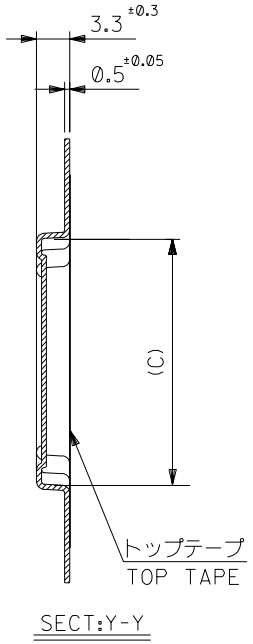
SHEET NO. 1 OF 2

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

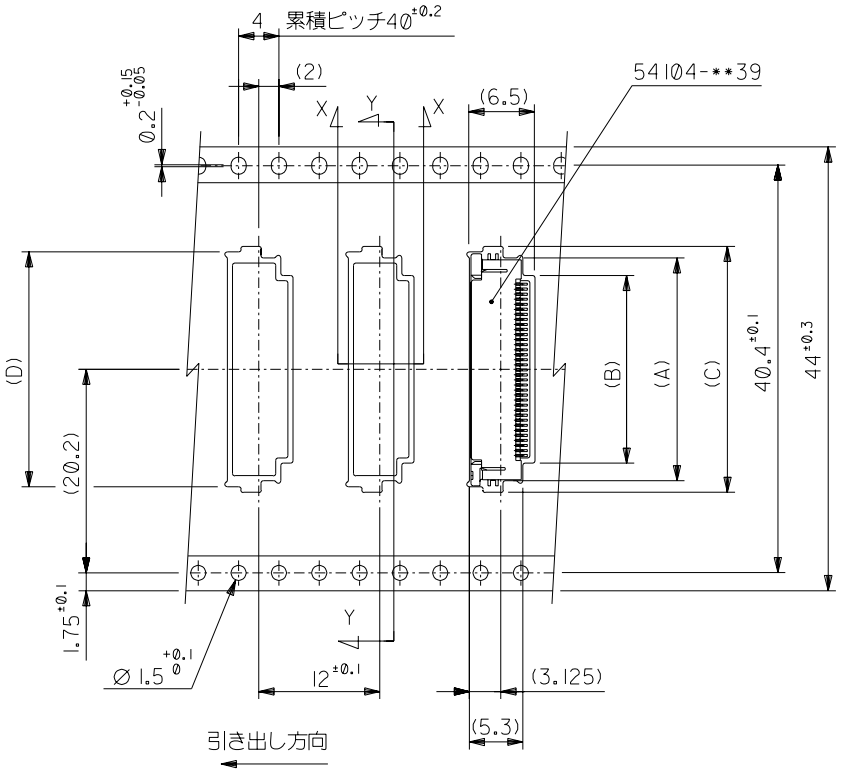
SIZE B

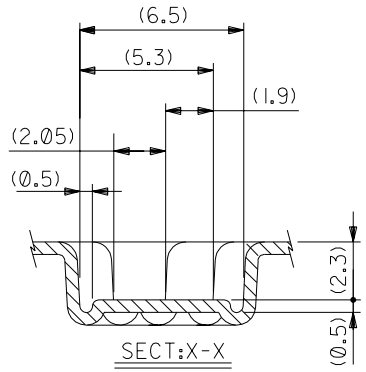
EN-02J(097) MXJ-54

DWG. NO. SD-54104-072



SECT:Y-Y





SECT:X-X
(SCALE:5-1)

DO NOT SCALE DRAWING

	EC NO.	DRWN:	CH'K:	APPR:
	EC NO.	DRWN:	CH'K:	APPR:
	EC NO.	DRWN:	CH'K:	APPR:
A	REVISED '04/04/21 EC NO. J2004-3918	DRWN: Y.WADA	CH'K: M.SASAO	APPR: M.SASAO
Ø	RELEASED '04/01/22 EC NO. J2004-2032	DRWN: Y.SAKIYAMA	CH'K: M.SASAO	APPR: M.SASAO

DESCRIPTION / REV

MATERIAL 材料: SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2

FINISH 仕上げ: //

WIRE RANGE 適用電線範囲: //

INS. RANGE 被覆外径: //

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差

10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

SCALE —

DESIGN UNITS ☒mm ☐INCH

THIRD ANGLE PROJECTION

MODEL NO. 54104-**96

DIMENSIONS: ☐mm/INCH ☐INCH/mm ☒mm ONLY

SHT REV

REVISE ON CAD ONLY

DRAWN BY & DATE Y.SAKIYAMA '04/01/22

CHECKED BY & DATE M.SASAO '04/01/22

APPROVED BY & DATE M.SASAO '04/01/22

TITLE: Embstp Pkg for 0.5 FPC Conn Zif Hsg Assy -LEAD FREE-

molex MOLEX INCORPORATED

CAD FILENAME SD-54104-072.S02

MATERIAL NO. SEE CHART

DRAWING NO. SD-54104-072

SHEET NO. 2 OF 2

SIZE B

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EN-02J(097) MXJ-54

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

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http://moschip.ru/get-element

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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moschip.ru_9